TECHNICAL SPEC FOR Track system

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System Model: DNS 80B SN 56700-3307
Tool status :
The tool, inclusive photoresist pumps, and the bypack units have been flushed and cleaned with solvent/DI water, and dry cleaned with CCA. The solvent lines (HMDS, Resist, thinner, developer have been disconnected from the tool), as well as the electric power supply lines. The bypacks of the tool are situated in the basement under the fab. The water cooling line and signal cables are still connected between process unit and bypack. Decommissioning was done by trained Litho technicians.
Wafer size: 6 inch
Wafer type: Jeida flat
Wafer flow:
Number coater/developer modules: 2C/3D
inLine system: Yes
Resists / Coaters: 4 (IDI)
DNS Develop nozzle kits: 3
RRC Pumps & kits:
Solvent & developer auto supply systems: Yes
Temperature / Humidity controller: Yes
Configuration/layout of each block:
GEM: yes
AVG:

HMDS Bubblers: HMDS bubbling system (2)

Power supply:

Vintage:

Missing parts: none

Defected parts: none

Operating system:

